

METHOD FOR BONDING OF CHIPS ON WAFERS

ABSTRACT

The invention relates to a method for bonding a plurality of individual chips (9) onto a base wafer (1), wherein the individual chips are stacked on the base wafer in multiple layers, and electrically conductive connections (7) exist between the vertically adjacent individual chips and the base wafer with the layer vertically adjacent to the base wafer, comprising the following steps in the order stated: a) fixing the base wafer onto a carrier (5), b) placing at least one layer of chips in defined positions on the base wafer, and c) thermal treatment of the chips on the base wafer fixed on the carrier.

Fig. 3b